MA3X152A (MA152A), MA3X152K (MA152K)

Silicon epitaxial planar type

For high-speed switching circuits

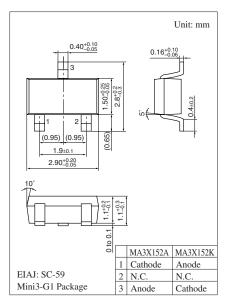
■ Features

- Short reverse recovery time t_{rr}
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current	I_{F}	100	mA
Peak forward current	I_{FM}	225	mA
Non-repetitive peak forward surge current *	I_{FSM}	500	mA
Junction temperature	Tj	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

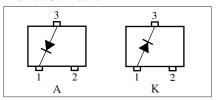
Note) *: t = 1 s



Marking Symbol

MA3X152A: MB
 MA3X152K: MI

Internal Connection

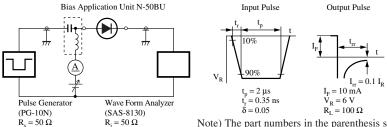


■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	MA3X152A	V_{F}	$I_F = 100 \text{ mA}$			1.2	V
	MA3X152K					1.2	
Reverse voltage		V_R	$I_R = 100 \mu A$	80			V
Reverse current		I_R	$V_R = 75 \text{ V}$			100	nA
Terminal capacitance		C _t	$V_R = 0 V, f = 1 MHz$			2	pF
Reverse recovery time *		t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			3	ns
			$I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$				

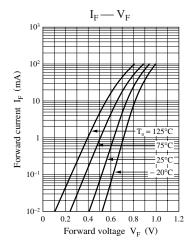
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring method for diodes.

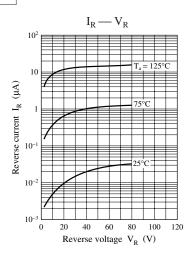
- 2. Absolute frequency of input and output is 100 MHz.
- 3. *: t_{rr} measurement circuit

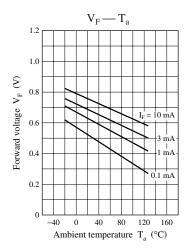


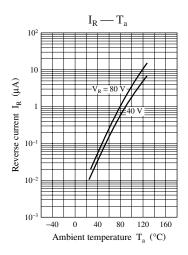
Note) The part numbers in the parenthesis show conventional part number.

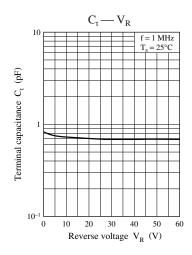
Characteristics chart of MA3X152A





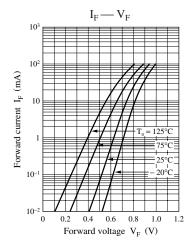


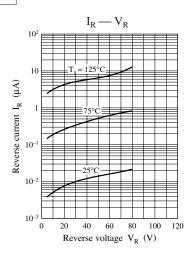


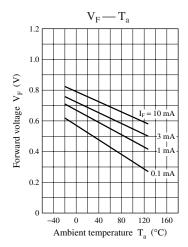


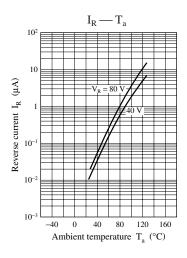
2 SKF00032CED

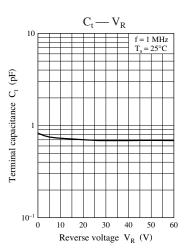
Characteristics chart of MA3X152K











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